

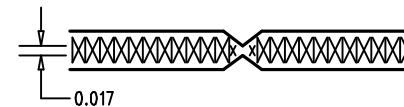
SHOWN FROM COMPONENT SIDE

REVISIONS			
REV	DESCRIPTION	APPR	DATE
A	PROTOTYPE RELEASE		


SIZE	QTY	SYM	PLTD
0.02	28	+	PLTD
0.07	3	X	NPLTD
0.035	12	□	PLTD
0.094	43	◇	PLTD
0.21	2	⊗	PLTD
0.125	4	⊗	PLTD

NOTES : Unless Otherwise Specified

1. MATERIAL : FR4 OR EQUIVALENT EPOXY, 2 OZ. COPPER CLAD
THICKNESS .062 +/- .006 TOTAL OF 2 LAYERS.
2. FINISH : ALL PLATED HOLES .001 MIN. / .0015 MAX. COPPER PLATE
ELECTRODEPOSITED TIN-LEAD COMPOSITION
BEFORE REFLOW , SOLDER MASK OVER BARE COPPER (SMOBC).
3. SOLDER MASK : BOTH SIDES USING LPI OR EQUIVALENT.
4. SILKSCREEN : USING WHITE NON-CONDUCTIVE EPOXY INK.
5. UNUSED SMD COMPONENTS SHOULD BE FREE OF SOLDER.
6. FILL UP ALL VIAS WITH SOLDER.
7. SCORING:



8. PLEASE LOOK AT THE README FILE FOR THE OTHER REQUIREMENTS.

APPROVALS			 LINEAR TECHNOLOGY 1630 McCarthy Blvd. Milpitas, CA 95035 PH: (408)432-1900	
DRAWN	INIT	DATE		
CHECK			TITLE: Fabrication Drawing SOFTWARE-SELECTABLE MULTIPROTOCOL TRANSCEIVER	
DESIGN	KIM T.	01-05-01		
ENGR	DAN E.	01-05-01	SIZE A DEMO DC327A LTC1546-LTC1545G REV. A	
SCALE = NONE			DES- 0000	SHT 1 of 1